CyberOptics’ 3D SPI Solution Fully ‘Connected’ to Panasonic NPM Mounter APC System

"CyberOptics’ 3D SPI Systems and CyberConnect™ software deliver real-time, continuous process improvements while reducing rework costs and increasing throughput with the Panasonic NPM Mounters"

Minneapolis, Minnesota — September 15, 2014 — CyberOptics® Corporation (NASDAQ: CYBE), a world leader in intelligent inspection and sensing solutions for electronics assembly and semiconductor process equipment, announces that all of its latest 3D SPI systems are now Panasonic Factory Automation APC (Adaptive Process Control) ready.

The CyberConnect™ program enables CyberOptics’ 3D SPI systems to successfully feed forward accurate X & Y offset data to Panasonic NPM mounters ensuring correct placement of components based on the solder printing position. CyberConnect™ delivers real-time, continuous process improvements while reducing rework costs and increasing production throughput. The feed forward program compliments other value-added process improvement packages from CyberOptics such as CyberPrint OPTIMIZER (automated print process optimization) and closed loop feedback with leading print vendors.

“We are pleased to be part of the Panasonic Factory Solutions APC program as another example of CyberOptics’ vision to offer process improvements at every stage of the manufacturing process,” stated Dennis Rutherford, VP Sales & Marketing of CyberOptics. “This is possible only when systems communicate with each other effectively in real time. With the latest trend in component miniaturization, feed forward capability with CyberConnect™ plays a critical role in accurate placement of 01005 and 03015 components.”

For more information, visit www.cyberoptics.com.

About Panasonic NPM (Next Production Modular)
The NPM (Next Production Modular) provides an integrated single-platform solution for expanding and evolving electronics assembly needs. In addition to its interchangeable, plug-and-play placement heads, the NPM platform integrates solder paste inspection (SPI), adhesive dispense (ADH), and post placement inspection (AOI).

About CyberOptics Corporation
Founded in 1984, CyberOptics Corporation is a leading provider of sensors and inspection systems that provide process yield and throughput improvement solutions for the global electronics assembly and semiconductor capital equipment markets. The Company’s products are deployed on production lines that manufacture surface mount technology circuit boards and semiconductor process equipment. Through internal development and acquisitions, CyberOptics is strategically repositioning itself to become a global leader in high-precision 3D sensors. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through facilities in North America, Asia and Europe.
Statements regarding the Company’s anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required for meeting customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; product introductions and pricing by our competitors; the level of revenue and loss we record in 2014; the success of our 3D technology initiatives; expectations regarding LDI and its impact on our operations; integration risks associated with LDI and other factors set forth in the Company’s filings with the Securities and Exchange Commission.

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